



Edge Computing, Big Data and Digital Twin towards Smart Manufacturing and Industry 5.0

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Message from the Guest Editors

Modern manufacturing industry practices have invested heavily in data transport from the factory floor to the cloud, where bulk process and monitoring data are analyzed in depth, leveraging the computing superiority and resource flexibility of a remote cloud infrastructure. Additionally, cloud processing renders difficult a trustworthy exchange of information between different industrial data providers in a certified manner. Data sharing already plays a crucial role in the manufacturing industry; either through data sharing for defect detection or through entire production chain provision and analysis, a significant amount of data are generated each second on the factory floor. The existing horizontal approach cannot encapsulate the interrelations between the different domain processes, actors and equipment in the OT environment, and each domain analysis remains isolated and monolithic. The goal of this Special Issue is to invite high-quality, state-of-the-art research papers that deal with challenging issues in the "Edge Computing, Big Data and Digital Twin towards Smart Manufacturing and Industry 5.0" applications and domain.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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